WHAT IS CLAIMED IS:

1. An electro-conductive metal plated polyimide substrate comprising an aromatic polyimide substrate, a subbing metal layer of Mo-Ni alloy comprising molybdenum and nickel in a weight ratio of 75/25 to 99/1, and a plated electro-conductive film.

2. The electro-conductive metal plated polyimide substrate of claim 1, in which the subbing metal layer of Mo-Ni alloy comprises molybdenum and nickel in a weight ratio of 75/25 to 95/5.

3. The electro-conductive metal plated polyimide substrate of claim 1, in which the electro-conductive metal comprises copper.

4. The electro-conductive metal plated polyimide substrate of claim 1, in which the aromatic polyimide substrate has a surface having been subjected to plasma treatment under reduced pressure, said surface being in contact with the subbing metal layer.

5. The electro-conductive metal plated polyimide substrate of claim 4, in which the surface of the aromatic polyimide substrate has a protrusions dispersed to form a network of protrusions.

6. The electro-conductive metal plated polyimide substrate of claim 1, in which the aromatic polyimide substrate comprises a biphenyltetracarboxylic acid component and a phenylenediamine component.

7. The electro-conductive metal plated polyimide substrate of claim 1, in which the aromatic polyimide film comprises a high heat resistant aromatic polyimide core layer comprising a biphenyltetracarboxylic acid component and a phenylene diamine component, and a pair of flexible aromatic polyimide surface layers comprising polyimide having a flexible bonding in a molecular structure thereof.

8. The electro-conductive metal plated polyimide substrate of claim 1, in which the subbing metal layer of Mo-Ni alloy has a thickness in the range of 2 to 30 nm.

9. The electro-conductive metal plated polyimide substrate of claim 1, in which the electroconductive film has a thickness in the range of 0.05 to 30 μm.

10. The electro-conductive metal plated polyimide substrate of claim 1, in which a sputtered copper metal layer is provided between the subbing metal layer and the plated electro-conductive metal film.

11. The electro-conductive metal plated polyimide substrate of claim 1, which satisfies the following requirements:

said polyimide substrate does not show any change of appearance when it is placed in an alkaline etching solution containing 2 wt.% of NaOH for 5 min., at 50°C; and

said polyimide substrate keeps a surface insulation resistance of $4 \times 10^{10}\Omega$ or higher in either case that it is placed in a ferric chloride solution or a cupric chloride solution.